



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Judy Huang

Serial No.: 09/336,525

Confirmation No.:

Filed: June 18, 1999

For: Plasma Treatment to Enhance
Adhesion and to Minimize
Oxidation of Carbon-Containing
Layers

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir or Madam:

§ Group Art Unit: 1762

§ Examiner: M. PADGETT

§ BEST AVAILABLE COPY 3/14/01

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on
2/28/01 with the United States Postal Service as First
Class Mail in an envelope addressed to: Assistant Commissioner for
Patents, Washington, D.C. 20231.

2/28/01

Kent Z. Taubz

Date

Signature

RESPONSE TO OFFICE ACTION DATED OCTOBER 31, 2000

In response to the Office Action dated October 31, 2000, having a shortened statutory period for response extended one month to expire on February 28, 2001, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. Applicant has submitted herewith a petition for one-month extension of time for filing this response.

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IN THE CLAIMS:

Please cancel claims 1-23.

1. (Canceled) A method of post-deposition treating a carbon-containing layer on a substrate, comprising exposing the carbon-containing layer to a treatment plasma.
2. (Canceled) The method of claim 1, wherein the carbon-containing layer comprises silicon carbide.